



LTCC SURFACE MOUNT

Band Pass Filter

BFCG-362+

50Ω 3.4 to 3.8 GHz

THE BIG DEAL

- Rugged, high-performance ceramic structure
- Compact 0805 footprint
- Robust 3 W continuous wave (CW) power handling

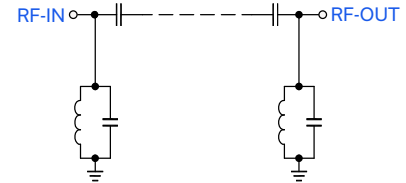


Generic photo used for illustration purposes only

APPLICATIONS

- WiMAX and LTE bands 42/43
- Mobile and fixed broadband access
- Enhanced mobile broadband (eMBB) for 5G

FUNCTIONAL DIAGRAM



PRODUCT OVERVIEW

Mini Circuits' BFCG-362+ band pass filter delivers high selectivity and low insertion loss across the 3.4–3.8 GHz band. A precision multilayer ceramic design ensures excellent stopband suppression and stable performance over $-55\text{ }^{\circ}\text{C}$ to $+105\text{ }^{\circ}\text{C}$. The ultra compact 0805 package minimizes board footprint and parasitics, making it a robust, space-efficient solution for demanding RF applications.

ELECTRICAL SPECIFICATIONS^{1,2,3} AT $+25\text{ }^{\circ}\text{C}$, $Z_0 = 50\Omega$

Parameter	F#	Frequency (GHz)	Min.	Typ.	Max.	Units	
Passband	Center Frequency ⁴	—	—	3.6	—	GHz	
	Insertion Loss	F10-F11	3.4 - 3.8	—	1.5	1.8	dB
	Return Loss	F10-F11	3.4 - 3.8	9.5	14.4	—	dB
Stopband, Lower	Rejection	F1-F2	0.5 - 2.17	—	38	—	dB
		F3-F4	0.88 - 0.96	—	40	—	
		F5-F6	1.71 - 1.785	—	38	—	
		F7-F8	2.3 - 2.63	—	30	—	
		F8-F9	2.63 - 2.7	—	25	—	
Stopband, Upper	Rejection	F12-F13	4.8 - 4.9	—	25	—	dB
		F13-F14	4.9 - 5.15	—	29	—	
		F14-F15	5.15 - 5.85	—	37	—	
		F16-F17	6.25 - 6.5	—	39	—	
		F18-F19	6.8 - 7.2	—	43	—	
		F19-F20	7.2 - 9	—	35	—	
		F21-F22	10.2 - 10.8	—	32	—	

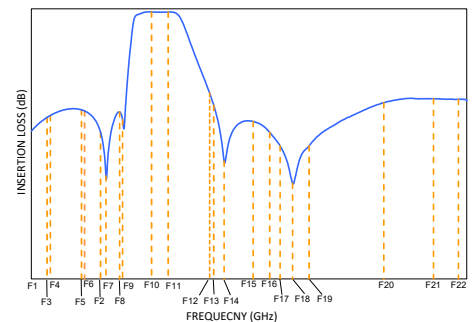
1. Tested in Evaluation Board P/N TB-BFCG-362C+. De-embedded to the device reference plane using TRL.
2. This filter is bi-directional RF1 and RF2 ports may be interchanged, see S-Parameters for actual performance.
3. This component should not be used as a DC-block. In applications where DC voltage and/or current is present at either the input or output ports, external DC blocking capacitors are required.
4. Typical variation $\pm 3\%$

ABSOLUTE MAXIMUM RATINGS⁵

Operating Temperature	$-55\text{ }^{\circ}\text{C}$ to $+105\text{ }^{\circ}\text{C}$
Storage Temperature	$-55\text{ }^{\circ}\text{C}$ to $+105\text{ }^{\circ}\text{C}$
Input Power ⁶	3 W

5. Permanent damage may occur if any of these limits are exceeded.
6. Power rating applies only to signals within the passband. Power rating above $+25\text{ }^{\circ}\text{C}$ operating temperature decreases linearly to 1.7 W at $+105\text{ }^{\circ}\text{C}$.

TYPICAL FREQUENCY RESPONSE





LTCC SURFACE MOUNT

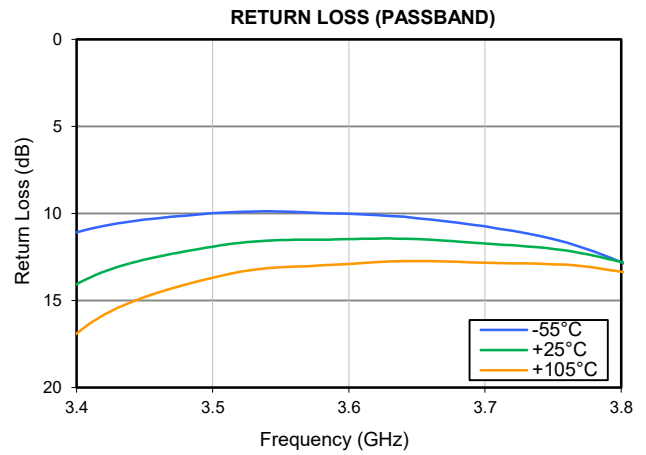
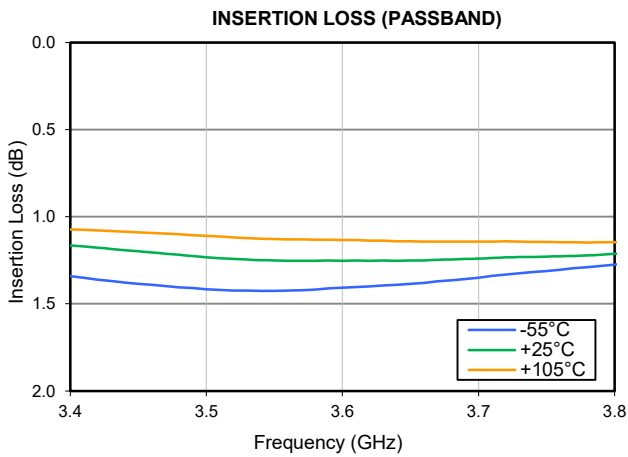
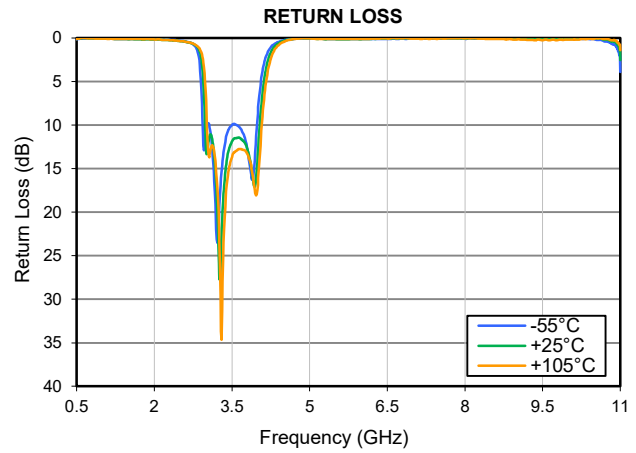
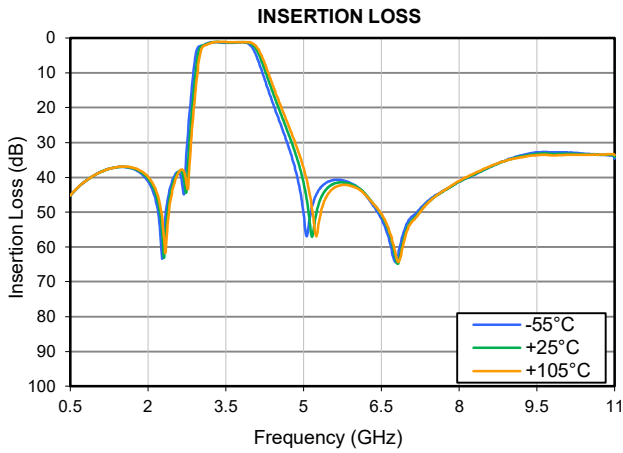
Band Pass Filter

BFCG-362+

Mini-Circuits

50Ω 3.4 to 3.8 GHz

TYPICAL PERFORMANCE GRAPHS





LTCC SURFACE MOUNT

Band Pass Filter

BFCG-362+

Mini-Circuits

50Ω 3.4 to 3.8 GHz

FUNCTIONAL DIAGRAM

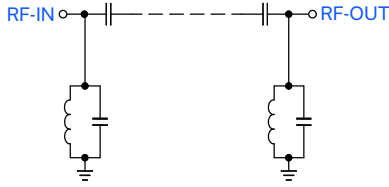
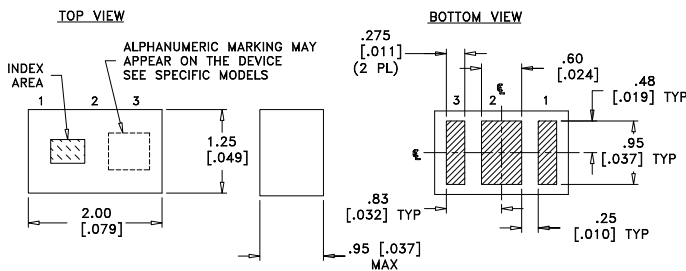


Figure 1. BFCG-362+ Functional Diagram

PAD DESCRIPTION

Function	Pad Number	Description
RF1 ²	1	Connects to RF Input Port
RF2 ²	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-853)

CASE STYLE DRAWING



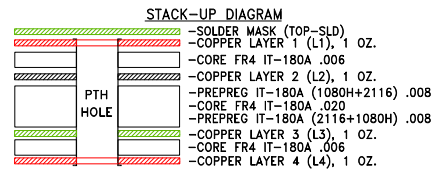
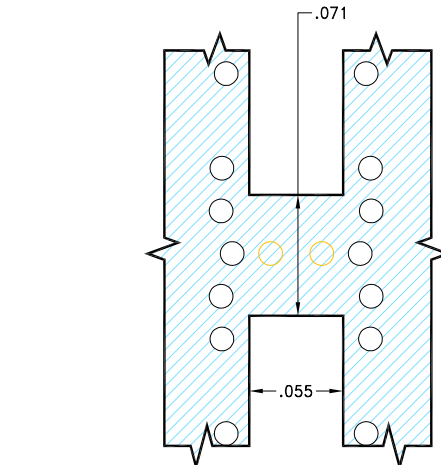
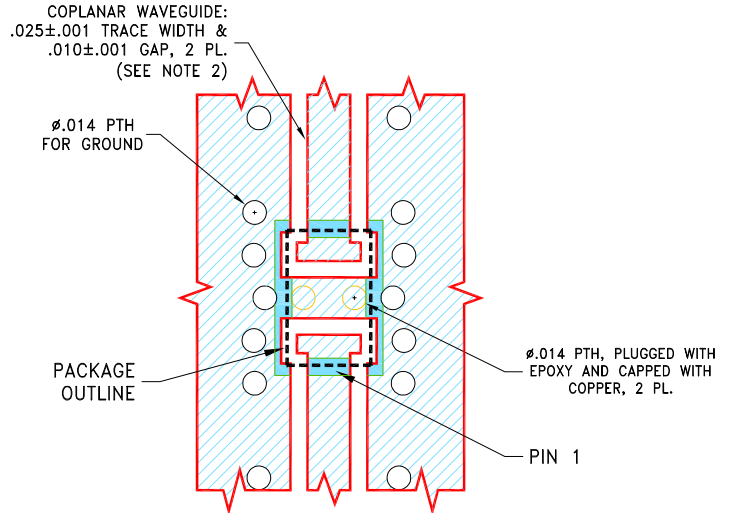
██████ DENOTES METALLIZATION

Weight: .010 grams
Dimensions are in mm [inches]. Tolerances: 2 Pl.± 0.05 mm

PRODUCT MARKING*: N/A

*Marking may contain other features or characters for internal lot control.

SUGGESTED PCB LAYOUT: PL-853



- TOTAL FINISHED THICKNESS 0.056±10%Φ.
- PTH PRESENT FROM COPPER LAYER 1 TO COPPER LAYER 4.

NOTES:

- PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
- TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR FR4 IT-180A WITH COMBINED DIELECTRIC THICKNESS .043"; FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- COPPER LAYERS 3,4 OF THE PCB ARE CONTINUOUS GROUND PLANES.

- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
- DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

Figure 2. Suggested PCB Layout



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ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASHBOARD

[CLICK HERE](#)

Performance Data & Graphs	Data Graphs S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	GE0805C-20 Lead Finish: Tin over Nickel Plating
RoHS/REACH Status	Compliant
Tape and Reel	F74
Suggested Layout for PCB Design	PL-853
Evaluation Board	TB-BFCG-362C+ Gerber File
Environmental Rating	ENV-159

NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html

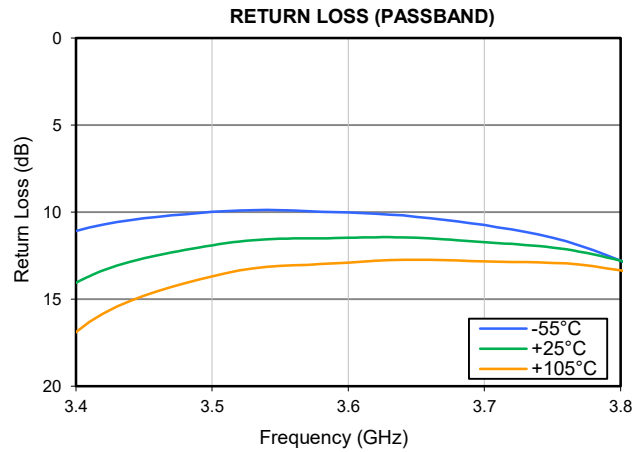
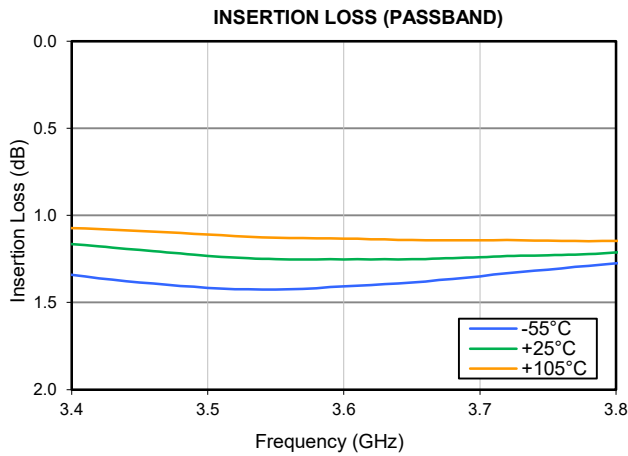
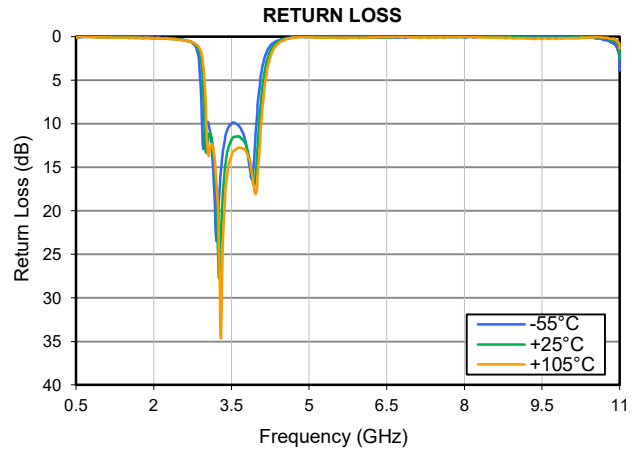
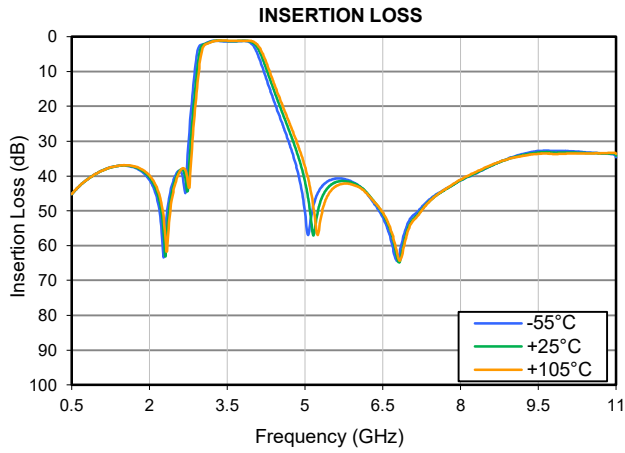


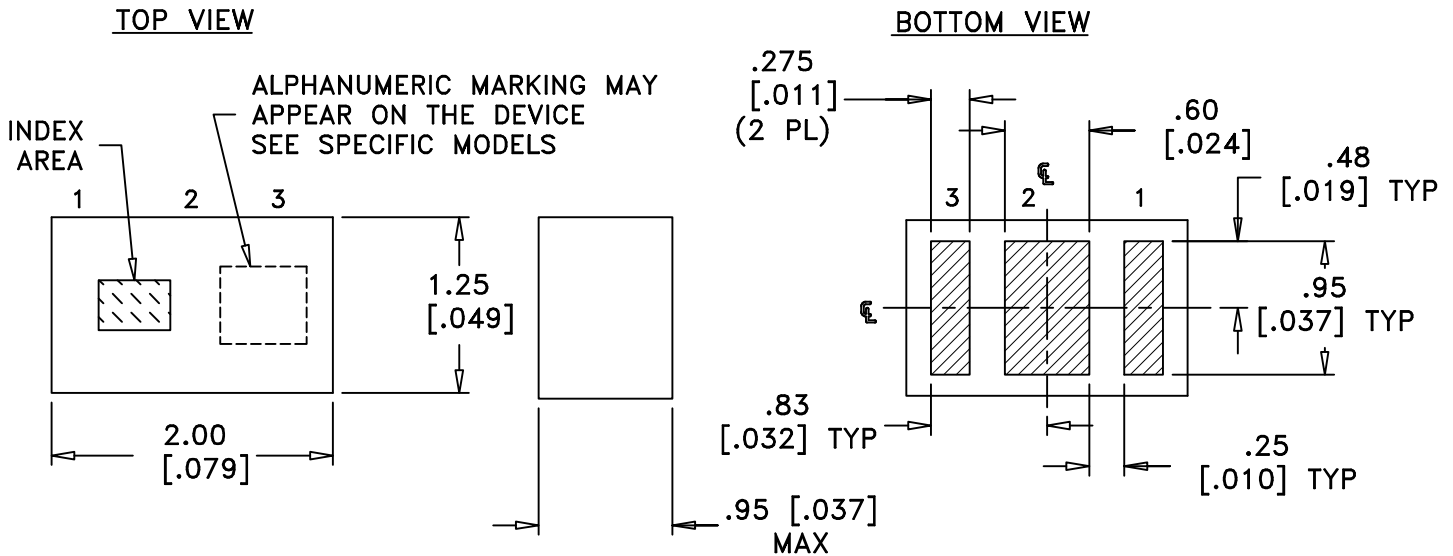
LTCC Bandpass Filter
Typical Performance Data

BFCG-362+

FREQUENCY (GHz)	INSERTION LOSS (dB)			RETURN LOSS (dB)		
	@-55°C	@+25°C	@+105°C	@-55°C	@+25°C	@+105°C
0.50	45.25	45.23	45.21	0.17	0.12	0.11
1.00	39.08	39.13	39.12	0.05	0.06	0.06
2.00	41.08	40.34	39.81	0.15	0.19	0.17
3.00	2.39	2.94	4.91	10.59	12.67	7.13
3.40	1.34	1.16	1.07	11.08	14.06	16.90
3.41	1.35	1.17	1.08	10.87	13.67	16.31
3.42	1.36	1.18	1.08	10.71	13.34	15.82
3.43	1.37	1.18	1.08	10.56	13.07	15.41
3.44	1.38	1.19	1.08	10.46	12.84	15.08
3.45	1.38	1.20	1.09	10.35	12.65	14.79
3.46	1.39	1.20	1.09	10.27	12.47	14.53
3.47	1.40	1.21	1.10	10.19	12.32	14.30
3.48	1.40	1.22	1.10	10.12	12.17	14.08
3.49	1.41	1.23	1.11	10.05	12.03	13.87
3.50	1.42	1.23	1.11	9.99	11.90	13.67
3.51	1.42	1.24	1.11	9.94	11.78	13.50
3.52	1.42	1.24	1.12	9.90	11.68	13.35
3.53	1.42	1.25	1.12	9.88	11.61	13.24
3.54	1.43	1.25	1.12	9.87	11.56	13.15
3.55	1.43	1.25	1.13	9.88	11.52	13.09
3.56	1.42	1.25	1.13	9.90	11.51	13.05
3.57	1.42	1.25	1.13	9.93	11.51	13.02
3.58	1.42	1.25	1.13	9.96	11.50	12.99
3.59	1.41	1.25	1.13	9.99	11.49	12.95
3.60	1.41	1.25	1.13	10.02	11.47	12.89
3.61	1.40	1.25	1.13	10.06	11.46	12.84
3.62	1.40	1.25	1.14	10.09	11.44	12.79
3.63	1.39	1.25	1.14	10.14	11.44	12.75
3.64	1.39	1.25	1.14	10.19	11.44	12.73
3.65	1.38	1.25	1.14	10.26	11.47	12.72
3.66	1.38	1.25	1.14	10.34	11.50	12.72
3.67	1.37	1.25	1.14	10.43	11.55	12.75
3.68	1.36	1.25	1.14	10.52	11.60	12.77
3.69	1.36	1.24	1.14	10.63	11.67	12.81
3.70	1.35	1.24	1.14	10.74	11.72	12.82
3.71	1.34	1.24	1.14	10.87	11.78	12.85
3.72	1.33	1.23	1.14	10.99	11.82	12.85
3.73	1.32	1.23	1.14	11.13	11.88	12.86
3.74	1.32	1.23	1.14	11.29	11.94	12.87
3.75	1.31	1.23	1.14	11.48	12.04	12.91
3.76	1.30	1.23	1.15	11.68	12.13	12.95
3.77	1.30	1.22	1.15	11.92	12.27	13.02
3.78	1.29	1.22	1.15	12.18	12.42	13.10
3.79	1.28	1.22	1.15	12.48	12.60	13.22
3.80	1.27	1.21	1.15	12.80	12.79	13.35
4.00	2.48	1.70	1.44	8.70	13.36	16.87
5.00	50.34	41.49	37.27	0.01	0.03	0.03
6.00	42.38	42.51	42.91	0.13	0.13	0.11
7.00	53.08	54.54	55.27	0.02	0.02	0.06
8.00	41.26	41.23	41.05	0.08	0.07	0.04
9.00	34.60	34.77	34.84	0.02	0.07	0.18
10.00	32.89	33.28	33.57	0.00	0.11	0.19
11.00	34.67	34.16	33.61	3.89	2.52	1.41

Typical Performance Data





DENOTES METALLIZATION

Weight: .010 grams

Dimensions are in mm[inches]. Tolerances: 2 Pl.±0.05mm

Notes:

1. **Open style, ceramic base.**
2. **Termination finish: Tin plate over Nickel plate.**
3. **Pad tolerance is non-cumulative. Minimum spacing between each pad is 0.1mm.**



P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F74

DEVICE ORIENTATION IN T&R

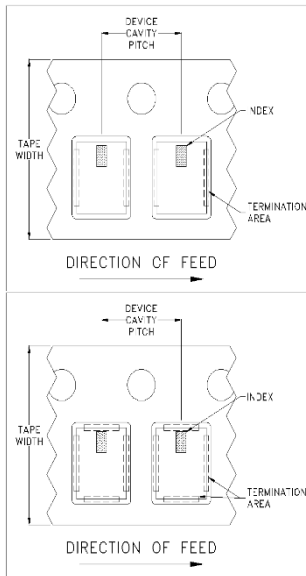


ILLUSTRATION 1

Applicable Case Styles

GE0805C-1
 GE0805C-1AP
 JV1210C-1
 GU2939

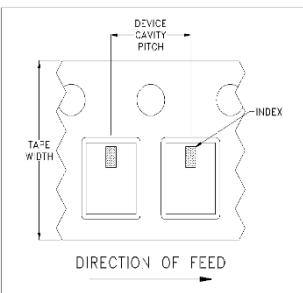


ILLUSTRATION 2

Applicable Case Styles

JV1210C
 JV1210C-2
 JV1210C-3
 JV1210C-4
 JV1210C-5
 JV1210C-6
 JV1210C-11

ILLUSTRATION 3

Applicable Case Styles

JC0603C-8
 JC0603C-9
 JV1210C-7
 JV1210C-8
 JV1210C-9
 JV1210C-10
 JV1210C-13
 GE0805C-13
 GE0805C-19
 GE0805C-20

Tape Width, mm	Device Cavity Pitch, mm	Real Size, inches	Devices per Reel	
8	4	7	Small quantity standards (see note)	20
				50
				100
				200
				500
				1000
			Standard	2000
				4000

Note: Small reel availability varies by model. Refer to pricing and availability on individual model dashboard.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

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**SUGGESTED MOUNTING CONFIGURATION
FOR GE0805C-20 CASE STYLE**

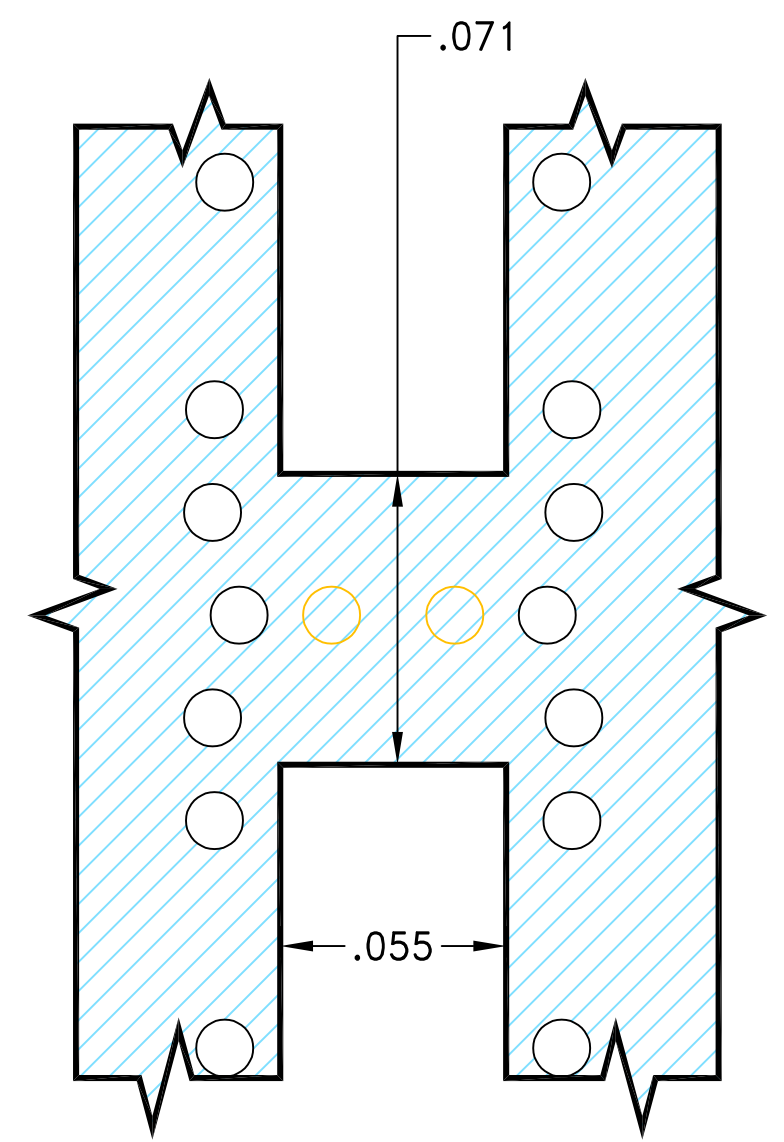
COPLANAR WAVEGUIDE:
.025±.001 TRACE WIDTH &
.010±.001 GAP, 2 PL.
(SEE NOTE 2)

∅.014 PTH
FOR GROUND

PACKAGE
OUTLINE

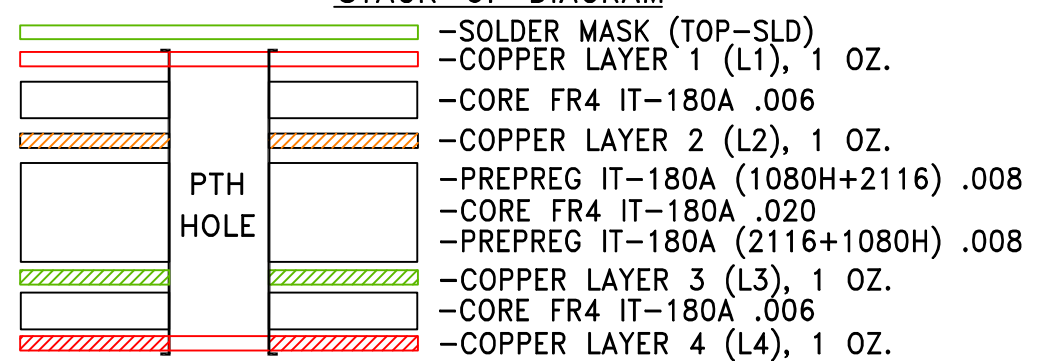
∅.014 PTH, PLUGGED WITH
EPOXY AND CAPPED WITH
COPPER, 2 PL.

PIN 1



TOP VIEW TO LAYER 2

STACK-UP DIAGRAM



- TOTAL FINISHED THICKNESS 0.056±10% ∅.
- PTH PRESENT FROM COPPER LAYER 1 TO COPPER LAYER 4.

NOTES:

- PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
- TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR FR4 IT-180A WITH COMBINED DIELECTRIC THICKNESS .043"; FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- COPPER LAYERS 3,4 OF THE PCB IS CONTINUOUS GROUND PLANES.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
 DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED	INITIALS	DATE
DIMENSIONS ARE IN INCHES	DRAWN ITG	12/17/26
TOLERANCES ON:	CHECKED NP	12/17/26
2 PL DECIMALS ±	APPROVED IL	12/17/26
3 PL DECIMALS ± .005		
ANGLES ± 1°		
FRACTIONS ±		

Mini-Circuits® 13 Neptune Avenue
Brooklyn NY 11235

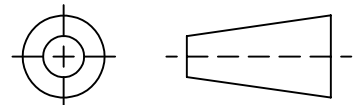
PL, GE0805C-20, TB-BFCG-362C+

OR	ECO-028525	NEW RELEASE	12/18/26	ITG	IL
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
REVISIONS					

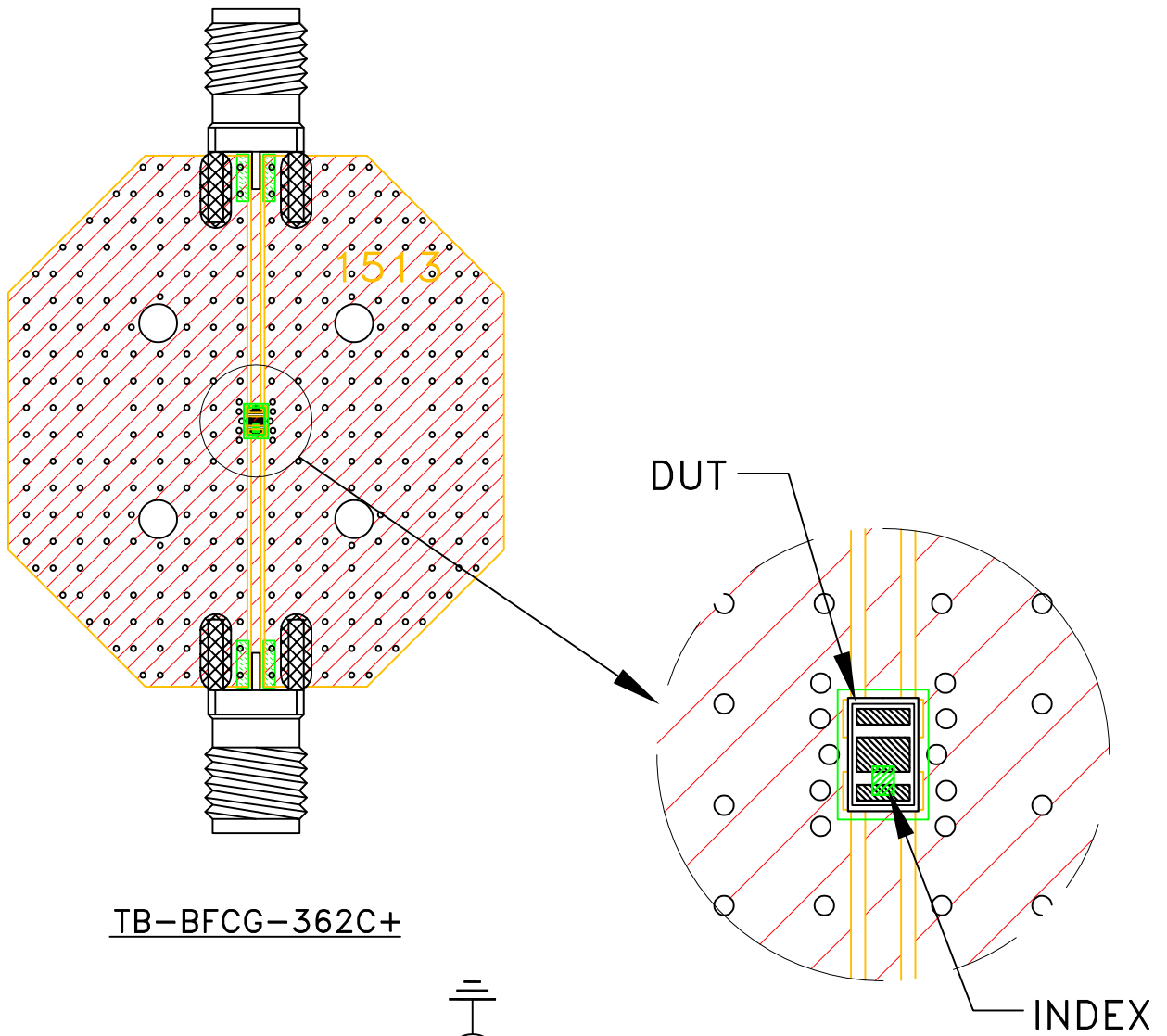
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SIZE B	CODE IDENT 15542	DRAWING NO: 98-PL-853	REV: OR
FILE: 98PL853	SCALE: 20:1	SHEET: 1 OF 1	

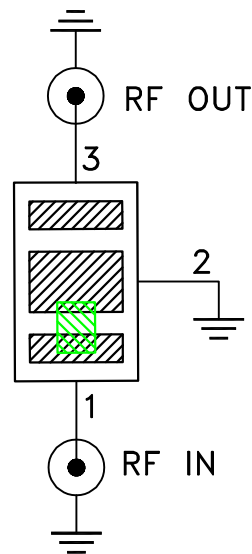
THIRD ANGLE PROJECTION



Evaluation Board and Circuit




TB-BFCG-362C+



Schematic Diagram

1. 50 Ohm SMA Female end Launch connectors.
2. PCB Material: FR4 IT-180A or equivalent,
Dielectric Constant= XXXX Thickness=.053 inch.

 Mini-Circuits®



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55°C to 105°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 105°C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 1000 hours, 85 +/- 2°C	JESD22-A101
Solderability	10X Magnification	MIL-STD-883 Method 2003:> 95% coverage
Thermal Shock	-40° C to 125° C, dwell time 30 min, 100 cycles	JESD22-A104